Notific	ation Number:	20200211001	P	CN Date:	Mar	ch 12, 2	020	
Title: Datasheet for MSP430FR2676, MSP430FR2675								
Custon	ner Contact: PC	CN Manager		Dept:		ept:	Quality Services	
Change	е Туре:							
	sembly Site	Desig	n			Wafer	Bump Site	
			X Data Sheet			Wafer Bump Material		
Assembly Materials		Part ı	Part number change			Wafer Bump Process		
Mechanical Specification		ion Test :	Test Site			Wafer Fab Site		
Packing/Shipping/Labeling		peling Test	Test Process			Wafer	Fab Materials	
☐ Wafer Fab Process								
Notification Details								
Description of Change:								
Texas Instruments Incorporated is announcing an information only notification.								
The product datasheet(s) is being updated as summarized below. The following change history provides further details.								
Texas								
INSTRUMENTS								
	from April 26, 2019 to	December 10, 2019		S	LASEO5	B-MARCH 20	019-REVISED DECEMBER 2019 Page	
Updated Section 1.1, Features								
Section 5.3, Recommended Operating Conditions								
• A	 Added the note that begins "TI recommends that power to the DVCC pin must not exceed the limits" in 							
Section 5.3, Recommended Operating Conditions								
Changed the note that begins "A capacitor tolerance of ±20% or better is required" in Section 5.3, Recommended Operating Conditions								
 Added the note "See MSP430 32-kHz Crystal Oscillators for details on crystal section, layout, and testing" to 								
Table 5-4, XT1 Crystal Oscillator (Low Frequency)								
Changed the note that begins "Requires external capacitors at both terminals" in Table 5-4, XT1 Crystal Oscillator (Low Frequency)								
Added the t _{TA,cap} parameter in Table 5-13, <i>Timer_A</i>								
Added the t _{TB can} parameter in Table 5-14, <i>Timer_B</i>								
• Corrected the test conditions for the R _I parameter in Table 5-21, ADC, Power Supply and Input Range Conditions. 44								
• C	 Added the note that begins "t_{Sample} = ln(2ⁿ⁺¹) × τ" in Table 5-22, ADC, Timing Parameters							
C	Characteristics							
Changed CRC covered end address to 0x1AF7 in table note (1) in Table 6-30 , Device Descriptors								
The datasheet number will be changing.								
Device Family			Change From:			Change	e To:	
MSP430FR2676, MSP430FR2675			SLASE05A			SLASEO5B		
These changes may be reviewed at the datasheet links provided.								
http://www.ti.com/produc/MSP430FR2675								
Reason for Change:								
To accurately reflect device characteristics.								
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):								
No anticipated impact. This is a specification change announcement only. There are no changes								
to the actual device.								
Changes to product identification resulting from this PCN:								
None.								
Product Affected:								
				MSP430FR2675TRHAR MSP430FR2675			MCD420ED2CZETSU	
		MSP430FR2675TP					MSP430FR2675TRHAT	
MSP43	0FR2675TRHBR	MSP430FR2675TRHBT		MSP430FR2	2676T	PT	MSP430FR2676TPTR	
MSP43	0FR2676TRHAR	MSP430FR2676TRHAT		MSP430FR2	676T	RHBR	MSP430FR2676TRHBT	

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